



HT78XX Series 500mA TinyPowerTM LDO

Features

- Output voltage ranges: Fixed range of 1.8V, 2.5V, 2.7V, 3.0V, 3.3V, 5.0V type.
- Highly accuracy: ±2%
- Low voltage drop: 360mV (typ.), V_{OUT}=5.0V at 500mA
- Guaranteed output current: 500mA

- Low quiescent current: 5μA (typ.)
- · Current limiting
- Over-temperature shutdown
- SOT-89, TO-92 Packages

Applications

- Battery powered systems
- Personal Digital Assistants
- Peripheral cards

- PCMCIA cards
- Personal Communication Equipment

General Description

The HT78XX series of positive, linear regulators features low quiescent current ($5\mu A$ typ.) with low dropout voltage, making them ideal for battery applications. The devices are capable of supplying 500mA of output current continuously.

They are available with several fixed output voltages ranging from 1.8V to 5.0V. Although designed primarily

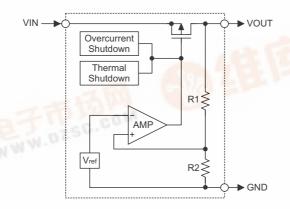
as fixed voltage regulators, these devices can be used with external components to obtain variable voltages and currents.

These rugged devices have Thermal Shutdown and Current Limiting to prevent device failure under the "Worst" of operating conditions.

Selection Table

Part No.	Output Voltage	Tolerance	Package
HT7818	1.8V		- BTIGG
HT7825	2.5V	_ / 45 (7	MWW.Dr.
HT7827	2.7V	+2%	SOT-89
HT7830	3.0V		TO-92
HT7833	3.3V		
HT7850	5.0V		

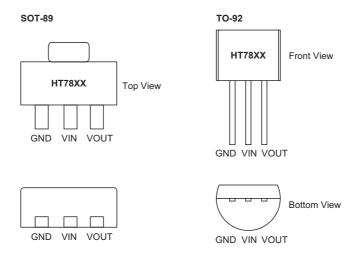
Block Diagram



1



Pin Assignment



Note: For lead free devices, a # mark is suffixed at the end of the date code.

Absolute Maximum Ratings*

Maximum Supply Voltage up to 8.5V	Storage Temperature50°C to 125°C
Operating Temperature40°C to 85°C	

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Thermal Information

Symbol	Parameter	Package	Max.	Unit
Thermal Resistance (Junction to Ambient)		SOT-89	200	°C/W
θ _{JA} (Assume no ambient airflow, no heat sink)	TO-92	200	°C/W	
P _D Power	Davier Dissipation	SOT-89	0.50	W
	Power Dissipation	TO-92	0.50	W

Note: P_D is measured at Ta= 25°C

Rev. 1.00 2 March 2, 2007

[&]quot;*" Absolute maximum ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. The guaranteed specifications apply only for the test conditions listed.



Electrical Characteristics

 T_j =25°C, V_{IN} = V_{OUT} +1.0V, I_O =1mA, unless otherwise specified

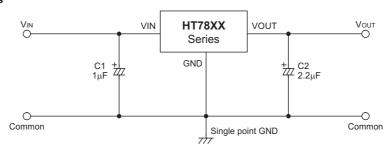
Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V _{IN}	Input Voltage	_				8	V
ΔV_{OUT}	Output Voltage Tolerance		_	-2	_	2	%
I _{SS}	Quiescent Current	I _O =0mA		_	5	7	μΑ
ΔV_{LOAD}	Load Regulation (Note1)	1mA≤l _{OUT} ≤500mA		_	0.004	0.008	%/mA
	Dropout Voltage (Note2) $ \frac{\Delta V_{OUT}=2\%}{I_{OUT}=500 \text{m/s}} $		V _O ≤1.8V	_	800	1200	
V _{DROP}			2.5V≤V _O ≤2.7V	_	500	650	mV
		1001 00011111	3.0V≤V _O ≤5.0V	_	360	500	
ΔV_{LINE}	Line Regulation	V _{OUT} +1.0V≤V _{IN} ≤8.0V		_	0.2	0.3	%/V
I _{LIM}	Current Limit (Note3)	ΔV _{OUT} =10%		500	_	_	mA
$\Delta V_{OUT} \over \Delta T_{a}$	Temperature Coefficient	_40°C <ta<85°c< td=""><td>_</td><td>±0.8</td><td>_</td><td>mV/°C</td></ta<85°c<>		_	±0.8	_	mV/°C

Note: 1. Load regulation is measured at a constant junction temperature, using pulse testing with a low ON time and is guaranteed up to the maximum power dissipation. Power dissipation is determined by the input/output differential voltage and the output current. Guaranteed maximum power dissipation will not be available over the full input/output range. The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - Ta) / \theta_{JA}.$

- 2. Dropout voltage is defined as the input voltage minus the output voltage that produces a 2% change in the output voltage from the value at $V_{IN} = V_{OUT} + 1V$ with a fixed load.
- 3. Current limit is measured by pulsing for a short time.

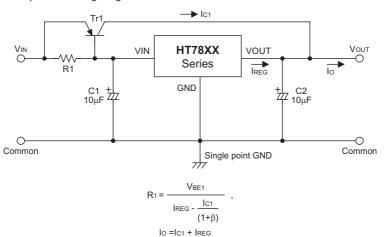
Application Circuits

Basic Circuits



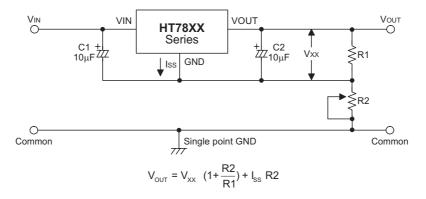
Typical Application Circuits

· High output current positive voltage regulator

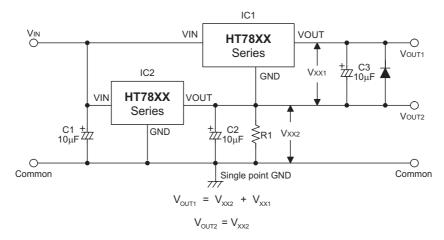




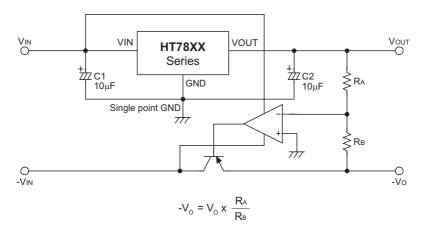
• Increased Output voltage Circuit



• Dual Supply Circuit



• Tracking Voltage Regulator

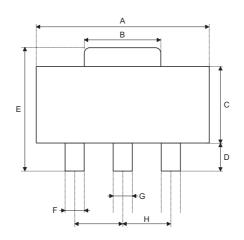


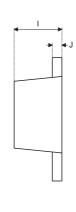
Rev. 1.00 4 March 2, 2007



Package Information

3-Pin SOT-89 Outline Dimensions

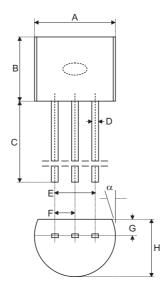




C. mah al		Dimensions in mil		
Symbol	Min.	Nom.	Max.	
А	173	_	181	
В	64	_	72	
С	90	_	102	
D	35	_	47	
E	155	_	167	
F	14	_	19	
G	17	_	22	
Н	_	59	_	
I	55	_	63	
J	14	_	17	



3-Pin TO-92 Outline Dimensions

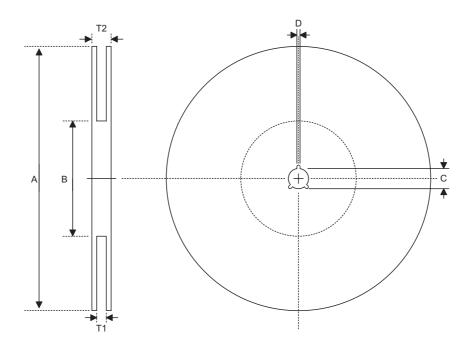


Cymrh al	Dimensions in mil			
Symbol	Min.	Nom.	Max.	
A	170	_	200	
В	170	_	200	
С	500	_	_	
D	11	_	20	
E	90	_	110	
F	45	_	55	
G	45	_	65	
Н	130	_	160	
I	8	_	18	
α	4°	_	6°	



Product Tape and Reel Specifications

Reel Dimensions

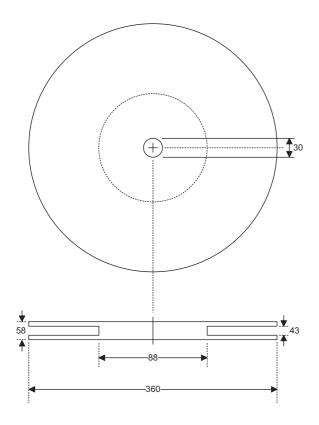


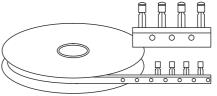
SOT-89

Symbol	Description	Dimensions in mm
Α	Reel Outer Diameter	180±1.0
В	Reel Inner Diameter	62±1.5
С	Spindle Hole Diameter	12.75+0.15
D	Key Slit Width	1.9±0.15
T1	Space Between Flange	12.4+0.2
T2	Reel Thickness	17–0.4

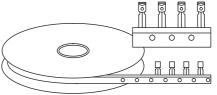


TO-92 Reel Dimensions (Unit: mm)





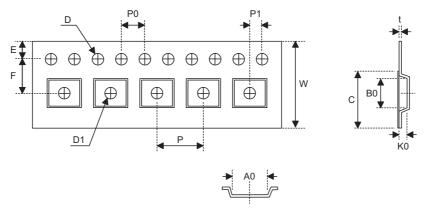
Package Up, Flat Side Up



Package Up, Flat Side Down



Carrier Tape Dimensions

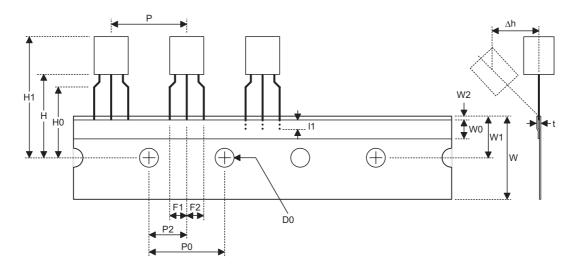


SOT-89

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	12.0+0.3 -0.1
Р	Cavity Pitch	8.0±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	5.5±0.05
D	Perforation Diameter	1.5+0.1
D1	Cavity Hole Diameter	1.5+0.1
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.10
A0	Cavity Length	4.8±0.1
В0	Cavity Width	4.5±0.1
K0	Cavity Depth	1.8±0.1
t	Carrier Tape Thickness	0.30±0.013
С	Cover Tape Width	9.3



TO-92 Carrier Tape Dimensions



TO-92

Symbol	Description	Dimensions in mm
I1	Taped Lead Length	(2.5)
Р	Component Pitch	12.7±1.0
P ₀	Perforation Pitch	12.7±0.3
P ₂	Component to Perforation (Length Direction)	6.35±0.4
F ₁	Lead Spread	2.5+0.4 -0.1
F ₂	Lead Spread	2.5+0.4 -0.1
Δh	Component Alignment	0±0.1
W	Carrier Tape Width	18.0+1.0 -0.5
W ₀	Hold-down Tape Width	6.0±0.5
W ₁	Perforation Position	9.0±0.5
W ₂	Hold-down Tape Position	(0.5)
H ₀	Lead Clinch Height	16.0±0.5
H ₁	Component Height	Less than 24.7
D_0	Perforation Diameter	4.0±0.2
t	Taped Lead Thickness	0.7±0.2
Н	Component Base Height	19.0±0.5

Note: Thickness less than 0.38±0.05mm~0.5mm

P0 Accumulated pitch tolerance: ± 1 mm/20pitches.

() Bracketed figures are for consultation only



Holtek Semiconductor Inc. (Headquarters)

No.3, Creation Rd. II, Science Park, Hsinchu, Taiwan Tel: 886-3-563-1999 Fax: 886-3-563-1189 http://www.holtek.com.tw

Holtek Semiconductor Inc. (Taipei Sales Office)

4F-2, No. 3-2, YuanQu St., Nankang Software Park, Taipei 115, Taiwan

Tel: 886-2-2655-7070 Fax: 886-2-2655-7373

Fax: 886-2-2655-7383 (International sales hotline)

Holtek Semiconductor Inc. (Shanghai Sales Office)

7th Floor, Building 2, No.889, Yi Shan Rd., Shanghai, China 200233 Tel: 86-21-6485-5560 Fax: 86-21-6485-0313 http://www.holtek.com.cn

Holtek Semiconductor Inc. (Shenzhen Sales Office)

5/F, Unit A, Productivity Building, Cross of Science M 3rd Road and Gaoxin M 2nd Road, Science Park, Nanshan District, Shenzhen, China 518057

Tel: 86-755-8616-9908, 86-755-8616-9308

Fax: 86-755-8616-9722

Holtek Semiconductor Inc. (Beijing Sales Office)
Suite 1721, Jinyu Tower, A129 West Xuan Wu Men Street, Xicheng District, Beijing, China 100031 Tel: 86-10-6641-0030, 86-10-6641-7751, 86-10-6641-7752

Fax: 86-10-6641-0125

Holtek Semiconductor Inc. (Chengdu Sales Office)

709, Building 3, Champagne Plaza, No.97 Dongda Street, Chengdu, Sichuan, China 610016 Tel: 86-28-6653-6590

Fax: 86-28-6653-6591

Holtek Semiconductor (USA), Inc. (North America Sales Office)

46729 Fremont Blvd., Fremont, CA 94538

Tel: 1-510-252-9880 Fax: 1-510-252-9885 http://www.holtek.com

Copyright © 2007 by HOLTEK SEMICONDUCTOR INC.

The information appearing in this Data Sheet is believed to be accurate at the time of publication. However, Holtek assumes no responsibility arising from the use of the specifications described. The applications mentioned herein are used solely for the purpose of illustration and Holtek makes no warranty or representation that such applications will be suitable without further modification, nor recommends the use of its products for application that may present a risk to human life due to malfunction or otherwise. Holtek's products are not authorized for use as critical components in life support devices or systems. Holtek reserves the right to alter its products without prior notification. For the most up-to-date information, please visit our web site at http://www.holtek.com.tw.

Rev. 1.00 11 March 2, 2007